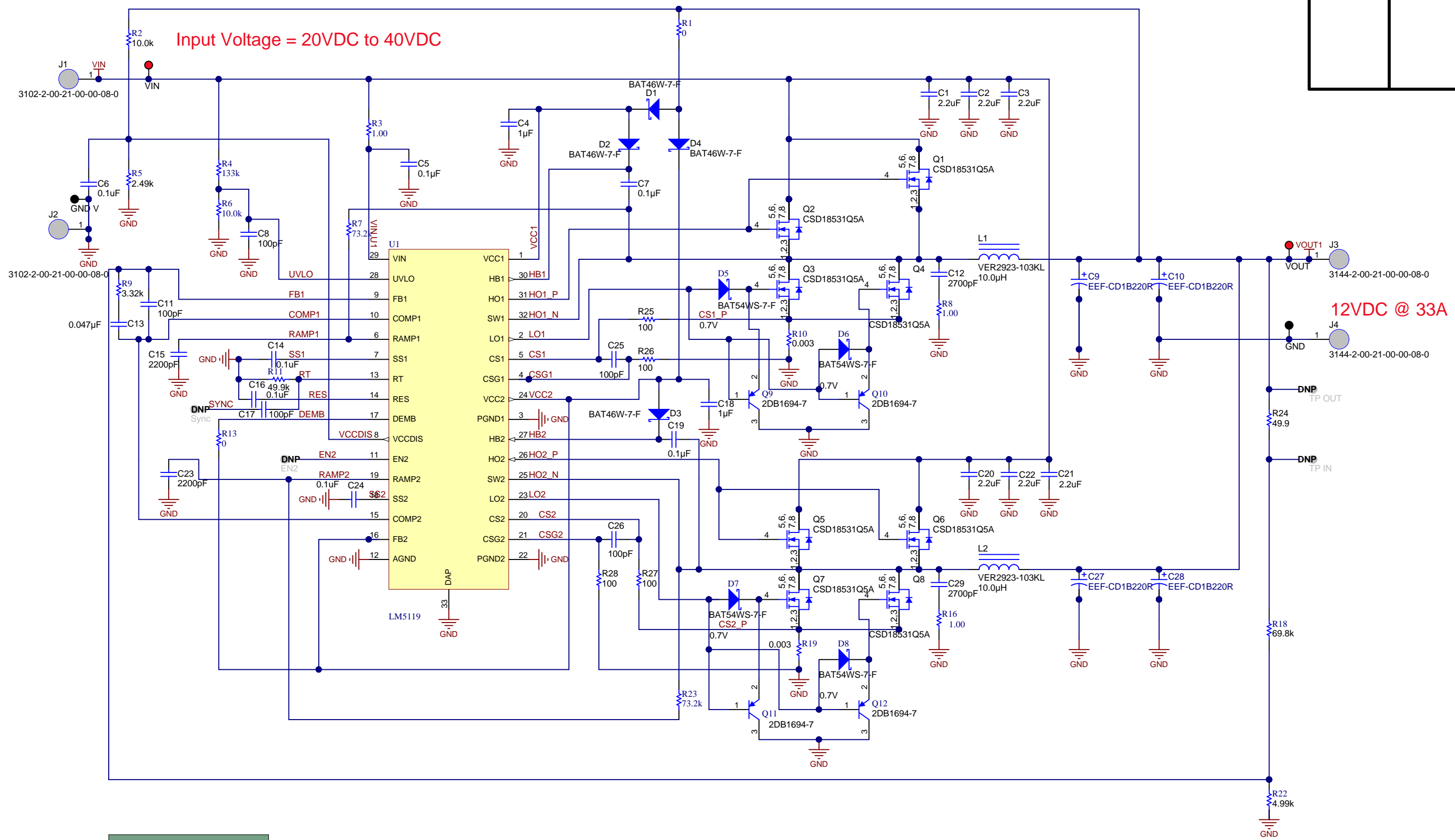


Revision History	
Revision	Notes
A	Built on PMP7819 Rev C PCB



PCB Assembly
PMP7819 REVC

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Orderable: N/A	Designed for: Public Release	Mod. Date: 3/9/2017
TID #: PMP20804	Project Title: LM5119 Dual Phase Synchronous Buck	
Number: PMP20804	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: PMP20804A.SchDoc	Size: B
Engineer: R. Sheehan	Contact: http://www.ti.com/support	



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